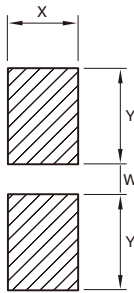


Recommended land pattern and size

(Vertical chip type)

● Standard type



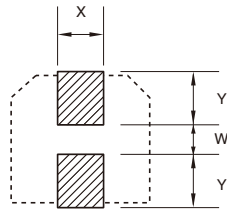
(Unit : mm)

Case Size φD×L	Land Size			Thickness of Solder paste
	X	Y	W	
4×5.3, 5.8	1.6	2.6	1.0	0.15
5×5.3, 5.8	1.6	3.0	1.4	0.15
6.3×5.3, 5.8, 7.7	1.6	3.6	1.9	0.15
8×6.5, 8.7	1.6	*4.0	*2.1	0.15
8×10, 10.5	2.5	*3.5	*3.0	0.15
10×8.7,10,10.5,12.5	2.5	*4.0	*4.0	0.15
12.5×13.5	3.2	6.0	4.0	0.15

* For Vibration resistance use
 φ8×6.5 Y=4.5 W=1.0
 φ8×10, φ8×10.5 Y=4.0 W=2.5
 φ10×10, φ10×10.5 Y=4.5 W=3.0
 φ10×12.5 Y=4.5 W=3.0

● For vibration resistance type

VTZ, VTD, VTT, VTQ, VTV, VTX, VMH, VMD, VMJ, VMF, VME, HT1, HTK, HTL, HTX, HTQ ,HTY series



(Unit : mm)

Case Size φD	Land Size			Thickness of Solder paste
	X	Y	W	
6.3	3.0	4.0	1.6	0.20
8	5.0	4.0	2.5	0.20
10	5.0	4.8	3.6	0.20
12.5	7.0	6.6	3.2	0.20
16	10.5	7.8	5.0	0.20
18	10.5	8.8	5.0	0.20